EPO-TEK® 730-110

Technical Data Sheet
For Reference Only
General Purpose Epoxy

Date:	February 2024	
Rev:	VII	
No. of Components:	Two	
Mix Ratio by Weight:	1 : 1	
Specific Gravity:	Part A: 1.17	Part B: 0.97
Pot Life:	1 Hour	
Shelf Life- Bulk:	One year at room temperature	

Recommended Cure: 80°C / 2 Hours

Minimum Alternative Cure(s):
May not achieve performance properties listed below
23°C / 24 Hours

NOTES:
- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: EPO-TEK® 730-110 is a two component, room temperature-curing, thermally and electrically insulating epoxy. It can be used for adhesive, sealing, potting or encapsulation applications found in semiconductor, electronics, and optical devices.

Typical Properties: Cure condition: Varies as required Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Clear/Colorless	Part B: Clear yellow
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 20 rpm:	8,000-12,000	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 50	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	61	x 10^{-6} in/in°C
Above Tg:	192	x 10^{-6} in/in°C
Shore D Hardness:	76	
Lap Shear @ 23°C:	> 2,000	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	343	°C
Weight Loss:		
@ 200°C:	1.01	%
Suggested Operating Temperature:	< 250	°C (Intermittent)
Storage Modulus:	129,916	psi
* Particle Size:	N/A	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	N/A	
Volume Resistivity @ 23°C:	≥ 4 x 10^{12}	Ohm-cm
Dielectric Constant (1KHz):	3.10	
Dissipation Factor (1KHz):	0.008	

OPTICAL PROPERTIES @ 23°C:		
Spectral Transmission:	≥ 95% @ 480-1,640	nm
Refractive Index (uncured):	1.5275 @ 589	nm

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EPO-TEK® 730-110 Advantages & Suggested Application Notes:

- Excellent "all-purpose adhesive". Many uses as a general purpose bonding solution. Commonly used in outdoor applications, automotive, industrial, and metal working applications.
- Designed as a medium viscosity flowing liquid but is also available as a thick paste (EPO-TEK® 730)
- Often applied by hand using a spatula or blade, by dispensing equipment, or directly from a bi-pack
- 1:1 mix ratio allows for easy mixing by volume or weight
- Adheres well to most surfaces including metal, foils, glass, ceramic, and many engineering plastics
- Versatile cure options ranging from 23°C (room temperature) to 80°C
    - For an ISO 10993 biocompatible version, see EPO-TEK® MED-730-110.

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